

New and Complete Claim Set

Delete claims 1-11

12. (Amended) A wafer-level package, comprising:
 - a first wafer and a second wafer;
 - a gasket ~~formed~~ etched from the material of the first wafer;
 - a pad on the second wafer, substantially matching the gasket; and
 - bonding material joining the gasket and the pad.
13. The wafer-level package of claim 12 wherein the first wafer is formed of silicon.
14. (Amended) The wafer-level package of claim 13 wherein the gasket is no more than 20 ~~um~~ um wide.
15. (Amended) The wafer-level package of claim 14 wherein the gasket is no more than 10 ~~um~~ um wide.
16. The wafer-level package of claim 14 wherein the bonding material includes conductive bonding material.
17. The wafer-level package of claim 16 wherein the conductive bonding material is a metal selected from the group consisting of gold, gold-tin, tin-lead, and palladium-tin.
18. The wafer-level package of claim 14 wherein the bonding material includes non-conductive bonding material.
19. The wafer-level package of claim 18 wherein the non-conductive bonding material is a material selected from the group consisting of polyimide, B-staged bisbenzocyclobutene (BCB), and glass.
20. (Amended) A wafer-level package, comprising:
 - a first wafer and a second wafer;
 - a gasket ~~formed~~ etched from the material of the first wafer; and
 - bonding material joining the gasket and the second wafer.
21. (Amended) The wafer-level package of claim 20, wherein the gasket is less than 20 ~~um~~ um wide.
22. (Amended) The wafer-level package of claim 21, wherein the gasket is less than 10 ~~um~~ um wide.

23. The wafer-level package of claim 21, wherein the bonding material is non-conductive.

24. The wafer-level package of claim 23, wherein the non-conductive bonding material is selected from the group consisting of polyimide, B-staged bisbenzocyclobutene (BCB), and glass.

A replacement copy of the claims is NOT included, as this application is part of the prototype program using image technology to replace paper processing.